



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

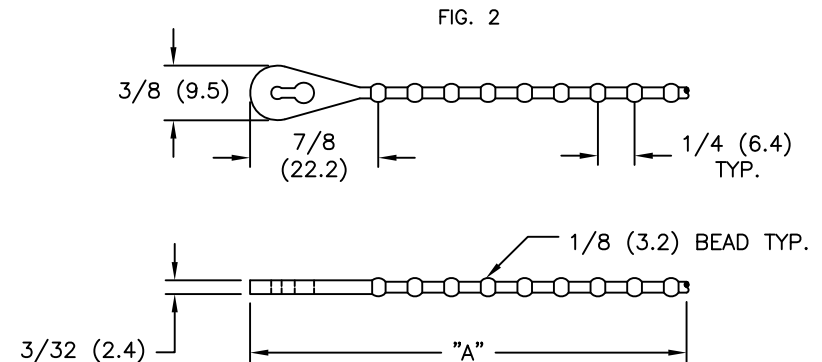
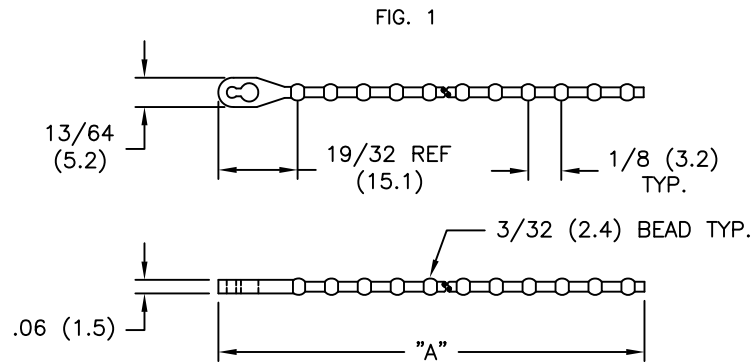
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



PART NO.	LENGTH "A" APPROX.	*MAX. BUNDLE DIA. REF.	MATERIAL: POLYPROPYLENE (RMS-10); COLOR: RED (-RD)	MATERIAL: POLYPROPYLENE (RMS-10); COLOR: YELLOW (-YL)	MATERIAL: POLYPROPYLENE (RMS-10); COLOR: BLUE (-BL)	MATERIAL: POLYPROPYLENE (RMS-10); COLOR: BLACK (-BK)	MATERIAL: NYLON 6/6 (RMS-01); COLOR: NATURAL AND BLACK	FIGURE NO.
BT-2	2.50 [63.5]	9/16 [14.3]	STANDARD	STANDARD	STANDARD	SPECIAL	SPECIAL	1
BT-4	4.00 [101.6]	1.00 [25.4]				STANDARD	SPECIAL	
BT-5	5.00 [127]	1-1/4 [31.8]						
BT-6	6.00 [152.4]	1-3/4 [44.5]				SPECIAL	STANDARD	
BT-8	8.75 [222.3]	2-3/8 [60.3]						
BT-10	10.75 [273.1]	3-1/8 [85.7]						
BT-12	12.75 [323.9]	3-5/8 [92.1]						
								2

\* ALL MAX. BUNDLE DIA. NEED 3 BEADS ENGAGEMENT.



D	SEE CO 200695	SK 07.26.11
C	SEE ECN #1089 FOR CHANGES	SK 11/01/05
B	ADDED DIM. .06 TO FIG. 1, RMS NO. TO MAT'L NOTE AND CHANGED FILE NO.	SM 08.03.01
A	MAX. BUNDLE DIA. ADDED	J.L. 9.17.97
REV	DESCRIPTION	ENGR DATE

TITLE: BEADED TIES				DWG IN IN (MM)	FINAL	
TOLERANCES UNLESS NOTED .XX=±.010 .XXX=±.005 FRAC=±1/64 ANG=±1°	FILE # BT	DWN: JB/PB	APP:	PART #		
	MAT'L: SEE TABLE	DT: 11-07-95	DT:	SEE TABLE	PRINT TYPE CA	
	RE: RICHCO, INC.	RICHCO INC. PO BOX 804238, CHICAGO, 60680 (773) 539-4060				